

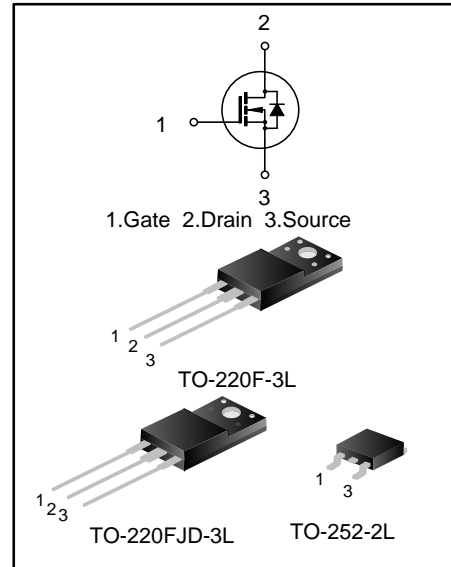
7A, 600V SUPER JUNCTION MOS POWER TRANSISTOR

DESCRIPTION

SVSP7N60F(FJD)(D)D2 is an N-channel enhancement mode high voltage power MOSFETs produced using Silan's super junction MOS technology. It achieves low conduction loss and switching losses. It leads the design engineers to their power converters with high efficiency, high power density, and superior thermal behavior. Furthermore, it's universal applicable, for example, it is suitable for hard and soft switching topologies.

FEATURES

- ◆ 7A,600V, $R_{DS(on)(typ.)}=0.48\Omega@V_{GS}=10V$
- ◆ New revolutionary high voltage technology
- ◆ Ultra low gate charge
- ◆ Enhanced avalanche capability
- ◆ Extreme dv/dt rated
- ◆ High peak current capability



ORDERING INFORMATION

Part No.	Package	Marking	Hazardous substance control	Packing Type
SVSP7N60FJDD2	TO-220FJD-3L	P7N60FJDD2	Halogen free	Tube
SVSP7N60DD2TR	TO-252-2L	P7N60DD2	Halogen free	Tape&Reel
SVSP7N60FD2	TO-220F-3L	P7N60FD2	Halogen free	Tube

ABSOLUTE MAXIMUM RATINGS (UNLESS OTHERWISE NOTED, T_A=25°C)

Characteristics	Symbol	Ratings		Unit
		SVSP7N60F/FJDD2	SVSP7N60DD2	
Drain-Source Voltage	V _{DS}	600		V
Gate-Source Voltage	V _{GS}	±30		V
Drain Current	I _D	T _C =25°C		7.0
		T _C =100°C		4.4
Drain Current Pulsed	I _{DM}	28		A
Power Dissipation (T _C =25°C) -Derate above 25°C	P _D	30	60	W
		0.24	0.48	W/°C
Single Pulsed Avalanche Energy (Note 1)	E _{AS}	255		mJ
Reverse diode dv/dt (Note 2)	dv/dt	15		V/ns
MOSFET dv/dt ruggedness (Note 3)	dv/dt	50		V/ns
Operation Junction Temperature Range	T _J	-55~+150		°C
Storage Temperature Range	T _{stg}	-55~+150		°C

THERMAL CHARACTERISTICS

Characteristics	Symbol	Ratings		Unit
		SVSP7N60F/FJDD2	SVSP7N60DD2	
Thermal Resistance, Junction-to-Case	R _{θJC}	4.17	2.08	°C/W
Thermal Resistance, Junction-to-Ambient	R _{θJA}	62.5	62.0	°C/W

ELECTRICAL CHARACTERISTICS (UNLESS OTHERWISE NOTED, $T_J=25^{\circ}\text{C}$)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Drain -Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	600	--	--	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=600V, V_{GS}=0V$	--	--	1.0	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 30V, V_{DS}=0V$	--	--	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2.0	--	4.0	V
Static Drain- Source on State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=3.5A$	--	0.48	0.58	Ω
Gate Resistance	R_g	$f=1.0\text{MHz}$	--	4.5	--	Ω
Input Capacitance	C_{iss}	$V_{DS}=100V, V_{GS}=0V,$ $f=1.0\text{MHz}$	--	427	--	pF
Output Capacitance	C_{oss}		--	26	--	
Reverse Transfer Capacitance	C_{rss}		--	1.9	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=300V, I_D=7.0A,$ $V_{GS}=10V, R_G=24\Omega$ (Note 4,5)	--	11	--	ns
Turn-on Rise Time	t_r		--	29	--	
Turn-off Delay Time	$t_{d(off)}$		--	43	--	
Turn-off Fall Time	t_f		--	25	--	
Total Gate Charge	Q_g	$V_{DS}=480V, I_D=7.0A,$ $V_{GS}=10V$ (Note 4,5)	--	16	--	nC
Gate-Source Charge	Q_{gs}		--	3.8	--	
Gate-Drain Charge	Q_{gd}		--	8.3	--	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	I_S	Integral Reverse P-N Junction	--	--	7.0	A
Pulsed Source Current	I_{SM}	Diode in the MOSFET	--	--	28	
Diode Forward Voltage	V_{SD}	$I_S=7.0A, V_{GS}=0V$	--	--	1.4	V
Reverse Recovery Time	T_{rr}	$I_S=7.0A, V_{GS}=0V,$	--	344	--	ns
Reverse Recovery Charge	Q_{rr}	$di/dt=100A/\mu s$ (Note 4)	--	2.6	--	μC

Notes:

- $L=79\text{mH}, I_{AS}=2.4A, V_{DD}=100V, R_G=25\Omega,$ starting temperature $T_J=25^{\circ}\text{C};$
- $V_{DS}=0\sim 400V, I_{SD}\leq 7.0A, T_J=25^{\circ}\text{C};$
- $V_{DS}=0\sim 480V;$
- Pulse Test: Pulse width $\leq 300\mu s,$ Duty cycle $\leq 2\%;$
- Essentially independent of operating temperature.

TYPICAL CHARACTERISTICS

Figure 1. On-Region Characteristics

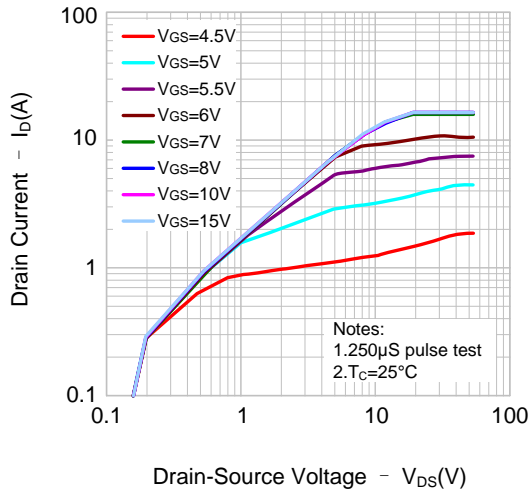


Figure 2. Transfer Characteristics

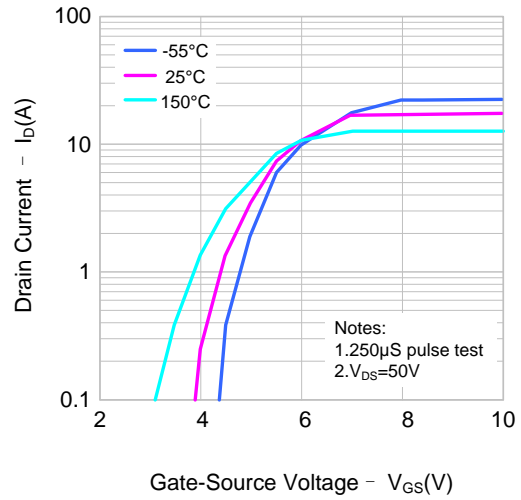


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

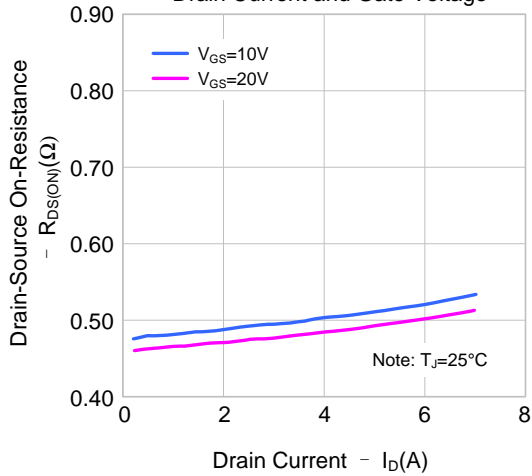


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

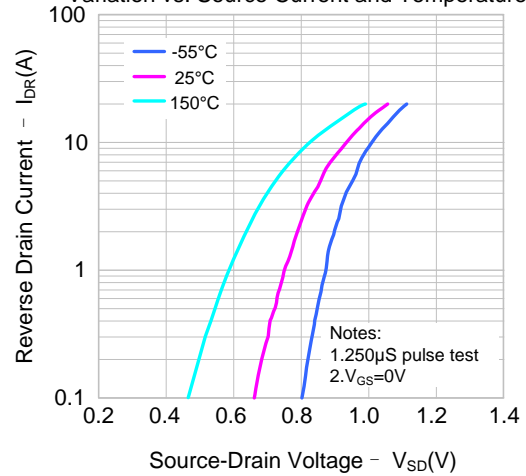


Figure 5. Capacitance Characteristics

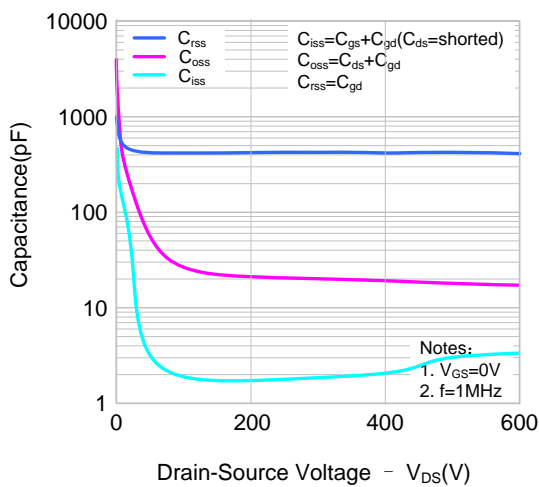
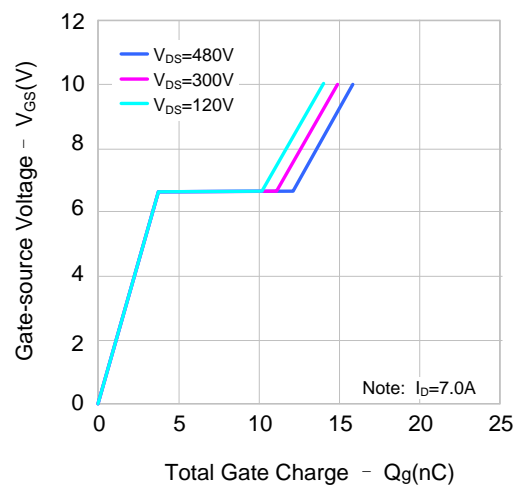


Figure 6. Gate Charge Characteristics



TYPICAL CHARACTERISTICS (CONTINUED)

Figure 7. Breakdown Voltage Variation vs. Temperature

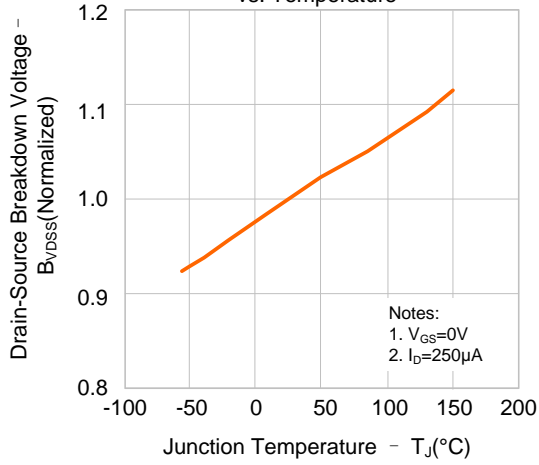


Figure 8. On-resistance Variation vs. Temperature

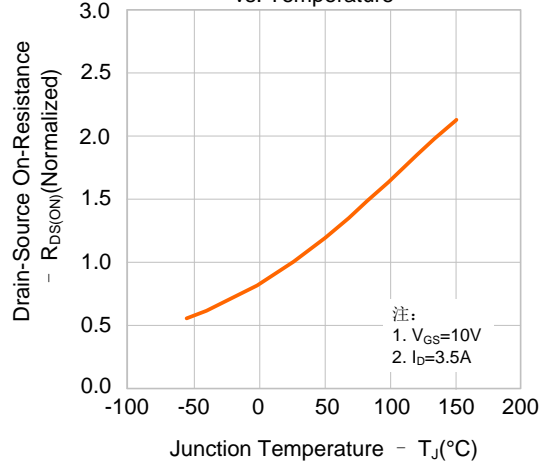


Figure 9-1. Max. Safe Operating Area (SVSP7N60F/FJDD2)

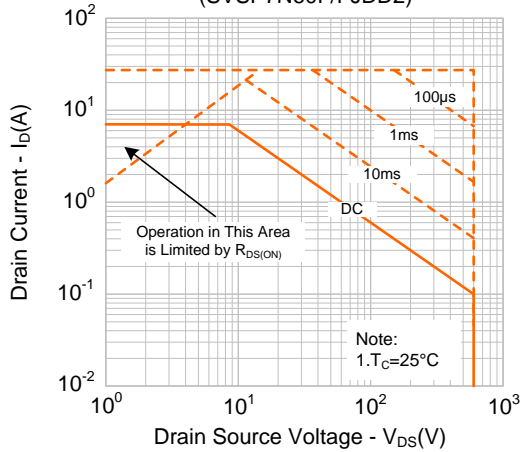
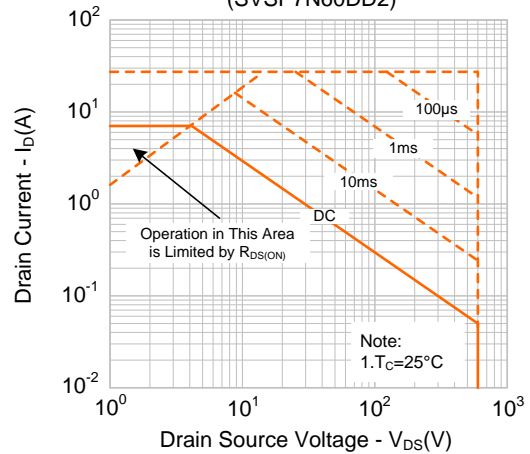
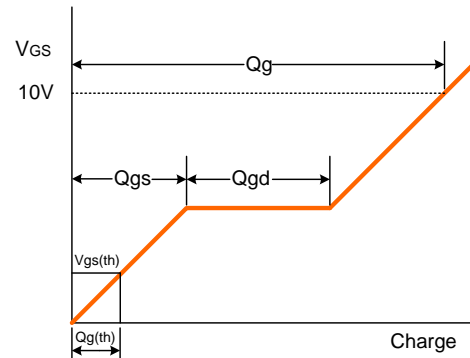
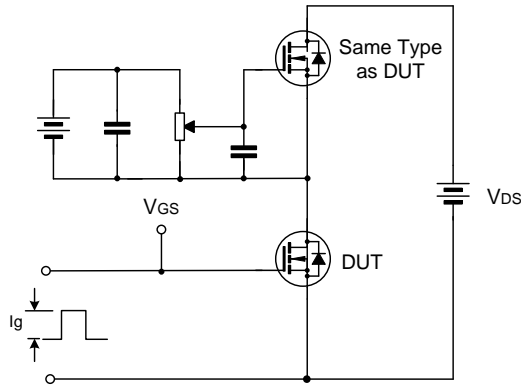


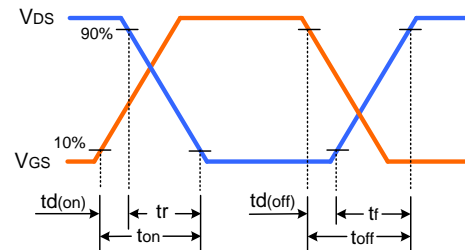
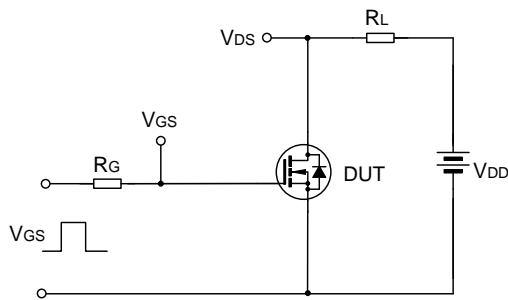
Figure 9-2. Max. Safe Operating Area (SVSP7N60DD2)



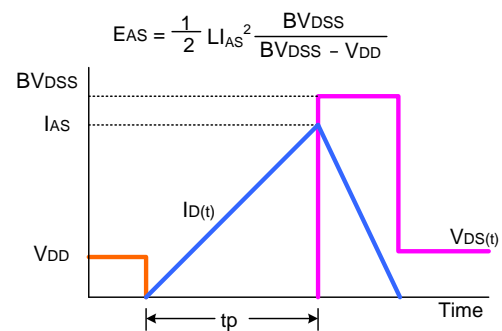
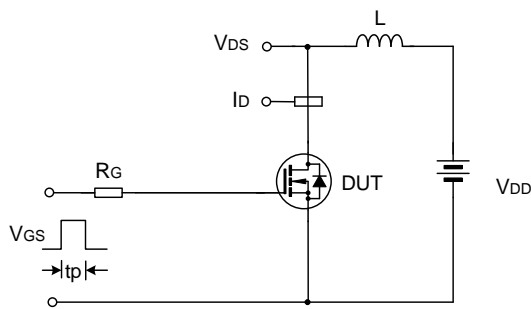
TYPICAL TEST CIRCUIT



Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform

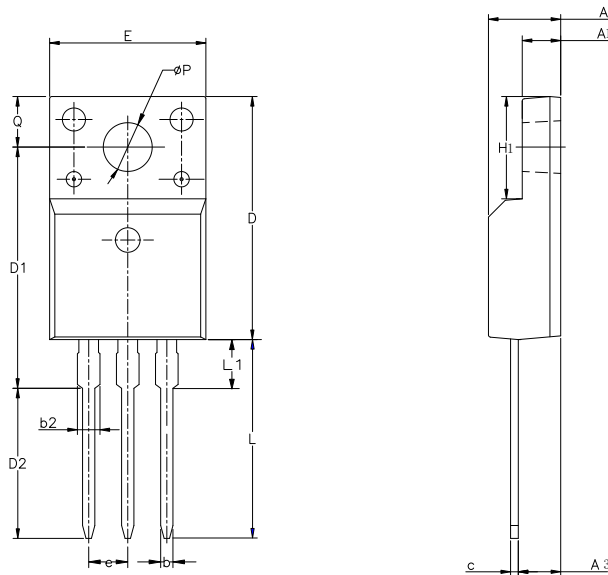


Unclamped Inductive Switching Test Circuit & Waveform

PACKAGE OUTLINE

TO-220FJD-3L

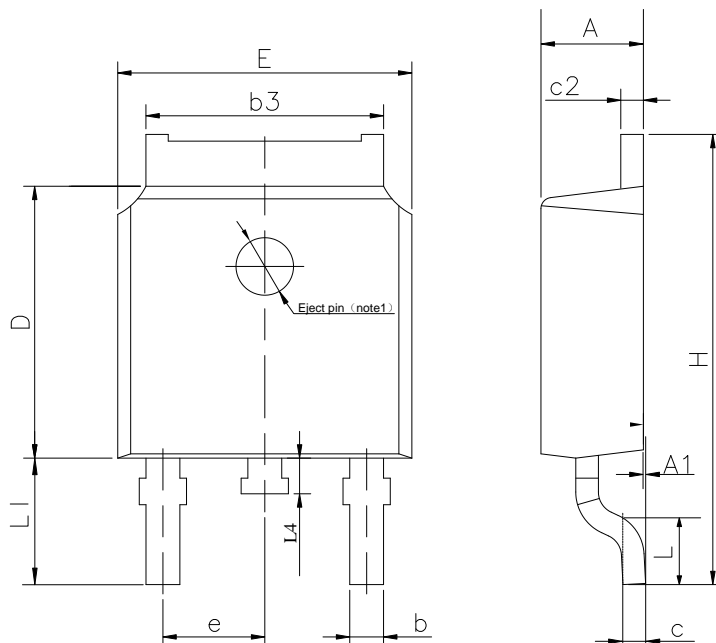
UNIT: mm



SYMBOL	MIN	NOM	MAX
A	4.42	4.70	5.02
A1	2.30	2.54	2.80
A3	2.50	2.76	3.10
b	0.55	0.70	0.85
b2	—	—	1.29
c	0.35	0.50	0.65
D	15.25	15.87	16.25
D1	13.97	14.47	14.97
D2	10.58	11.08	11.58
E	9.73	10.16	10.36
e	2.54BCS		
H1	6.40	6.68	7.00
L	12.48	12.98	13.48
L1	—	—	2.00
ØP	3.00	3.18	3.40
Q	3.05	3.30	3.55

TO-252-2L

UNIT: mm



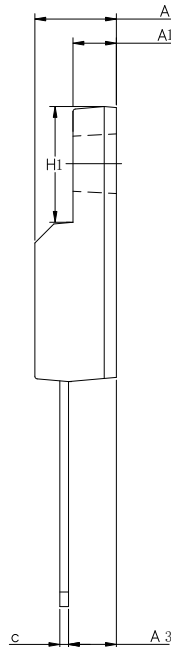
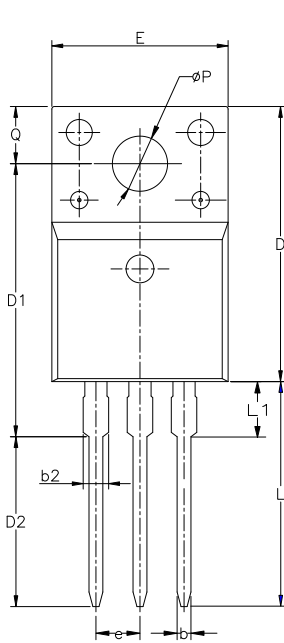
SYMBOL	MIN	NOM	MAX
A	2.10	2.30	2.50
A1	0	---	0.127
b	0.66	0.76	0.89
b3	5.10	5.33	5.46
c	0.45	---	0.65
c2	0.45	---	0.65
D	5.80	6.10	6.40
E	6.30	6.60	6.90
e	2.30TYP		
H	9.60	10.10	10.60
L	1.40	1.50	1.70
L1	2.90REF		
L4	0.60	0.80	1.00

NOTE1 : There are two conditions for this position:has an eject pin or has no eject pin.

PACKAGE OUTLINE(CONTINUED)

TO-220F-3L

UNIT: mm



SYMBOL	MIN	NOM	MAX
A	4.42	4.70	5.02
A1	2.30	2.54	2.80
A3	2.50	2.76	3.10
b	0.70	0.80	0.90
b2	—	—	1.47
c	0.35	0.50	0.65
D	15.25	15.87	16.25
D1	15.30	15.75	16.30
D2	9.30	9.80	10.30
E	9.73	10.16	10.36
e	2.54BCS		
H1	6.40	6.68	7.00
L	12.48	12.98	13.48
L1	/	/	3.50
ϕP	3.00	3.18	3.40
Q	3.05	3.30	3.55

Important notice :

- The instructions are subject to change without notice! Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current.
- Our products are consumer electronic products, and / or civil electronic products.
- When using our products, please do not exceed the maximum rating of the products, otherwise the reliability of the whole machine will be affected. There is a certain possibility of failure or malfunction of any semiconductor product under specific conditions. The buyer is responsible for complying with safety standards and taking safety measures when using our products for system design, sample and whole machine manufacturing, so as to avoid potential failure risk that may cause personal injury or property loss.
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Rev: 1.2

Revision History:

1. Modify Electrical schematic and TYPICAL TEST CIRCUIT
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Rev: 1.1

Revision History:

1. Update Fig 5
-

Rev: 1.0

Revision History:

1. First release
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